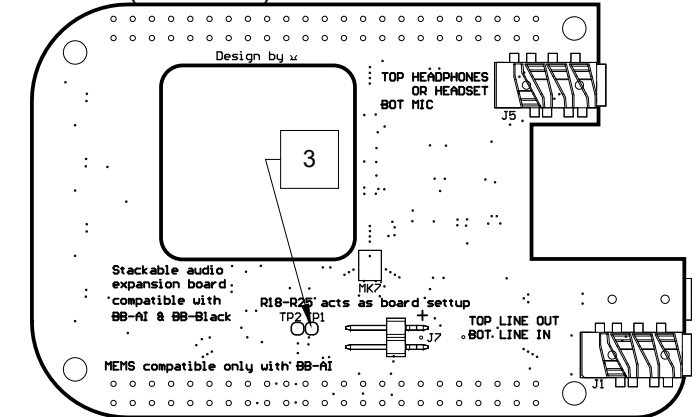
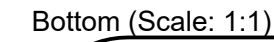
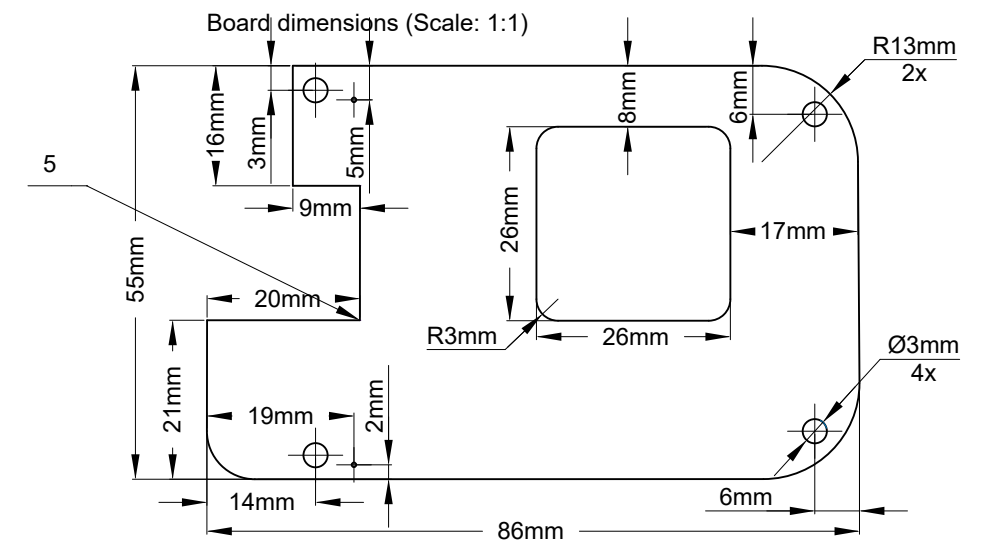
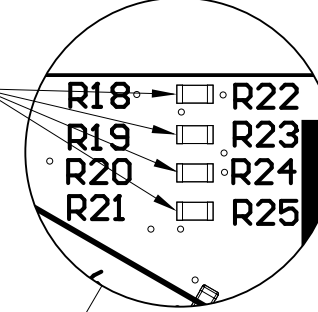
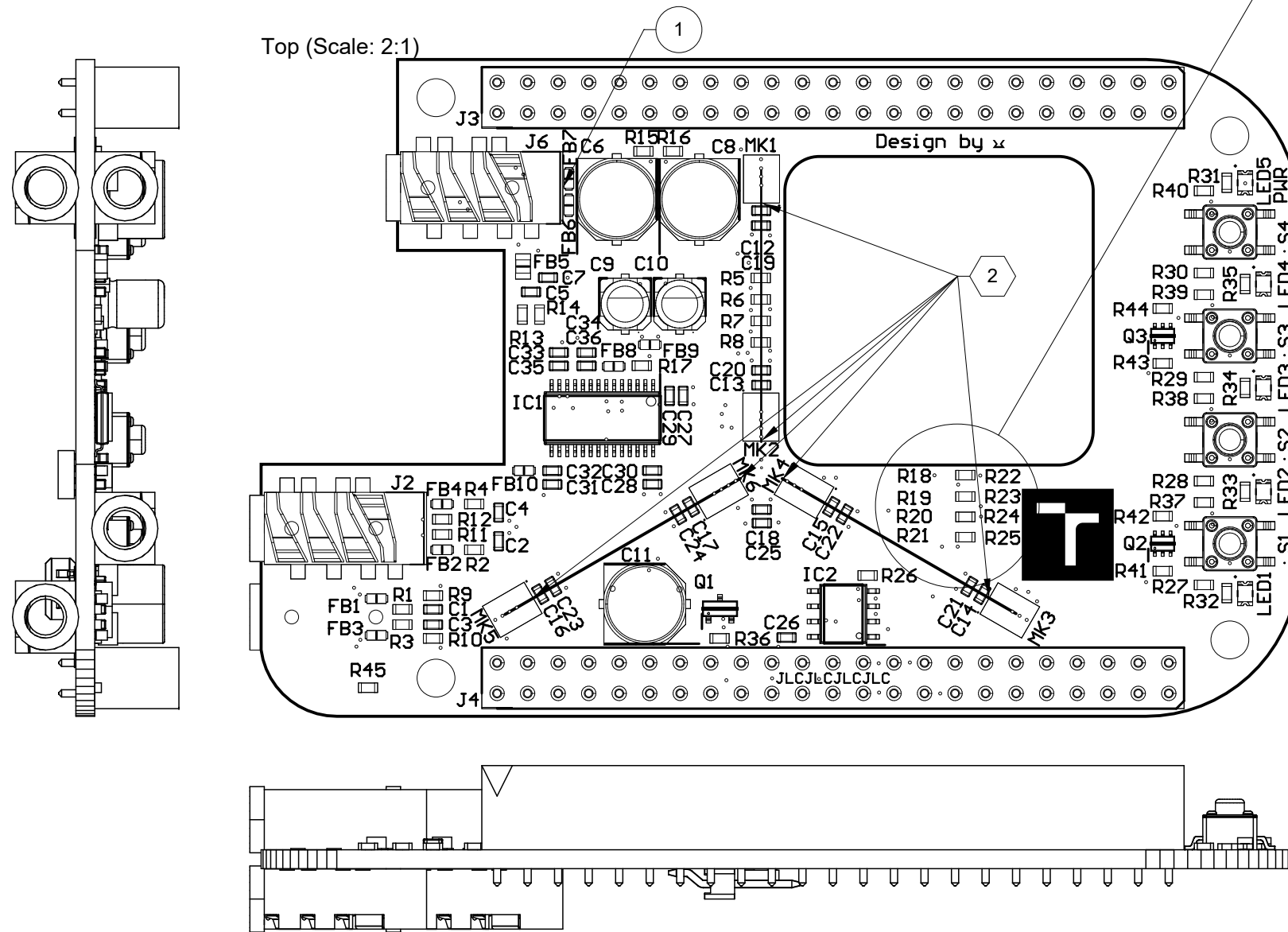
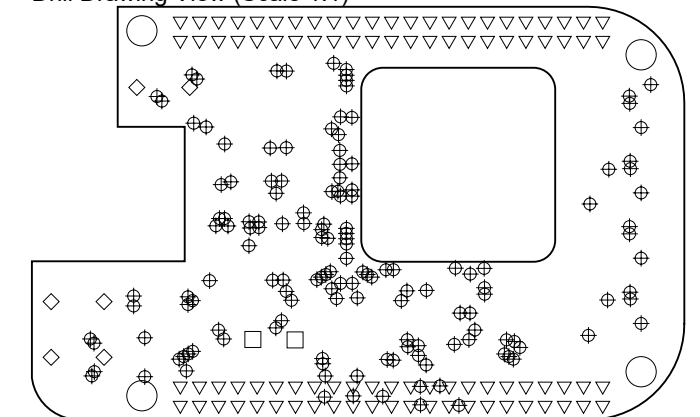


- ① If Headset is connected to Headphone connector J6 and Microphone input J5 is empty then the J6 acts as a microphone input.
- ② MESM microphones, capacitors C12-C25 and resistors R5-R8 are optional
- ③ EEPROM write protection is enabled by R26, to enable write connect TP1 & TP2 on bottom layer.
4. Minimum signal trace width: 5mil (0.127mm)
Minimum spacing between traces: 5mil (0.127mm)
5. Dimensions are converted from mil to mm and rounded

DETAIL A (Scale 6:2)



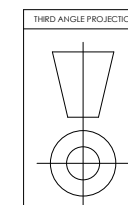
Drill Drawing View (Scale 1:1)



Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
	Surface Material	0.0127mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.0350mm		Signal	GTL
Prepreg		0.1000mm	2313	Dielectric	
Copper	Mid Layer 1	0.0175mm		Signal	G1
Core		1.2650mm	FR-4	Dielectric	
Copper	Mid Layer 2	0.0175mm		Signal	G2
Prepreg		0.1000mm	2313	Dielectric	
Copper	Bottom Layer	0.0350mm		Signal	GBL
Surface Material	Bottom Solder	0.0127mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.5954mm					

Resistor place	Left (R18 - R21)	Right (R22 - R25)
Codec I2C	0X1A	0X1B
EEPROM I2C	0X50	0X51
I2S Data In	PIN 9.26	PIN 9.30
I2S Data Out	PIN 9.28	PIN 9.41
MEMS Enable	ON	PIN 9.12

Symbol	Count	Hole Size	Plated	Hole Type	Via / Pad
⊕	148	0.30mm	Plated	Round	Via
□	2	0.50mm	Plated	Round	Via
▽	92	0.80mm	Plated	Round	Pad
◇	6	1.20mm	Plated	Round	Pad
○	4	3.20mm	Plated	Round	Pad
252 Total					



APPROVALS		DATE
ENGINEER:	Bc. Karel Benko	23.05.2022
DESIGNER:	Bc. Karel Benko	23.05.2022

REFERENCE DOCUMENTS	
BOM DOC:	BBAIAEB.BomDoc
ASSY DOC:	BBAIAEB_ASSY.PCBDwf
SCH DOC:	BBAIAEB.SchDoc
PCB DOC:	BBAIAEB.PcbDoc



SIZE:
A3
SCALE:

TITLE:

1.1

10

Beo
FILE NAME

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BRAI

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Audio Ex

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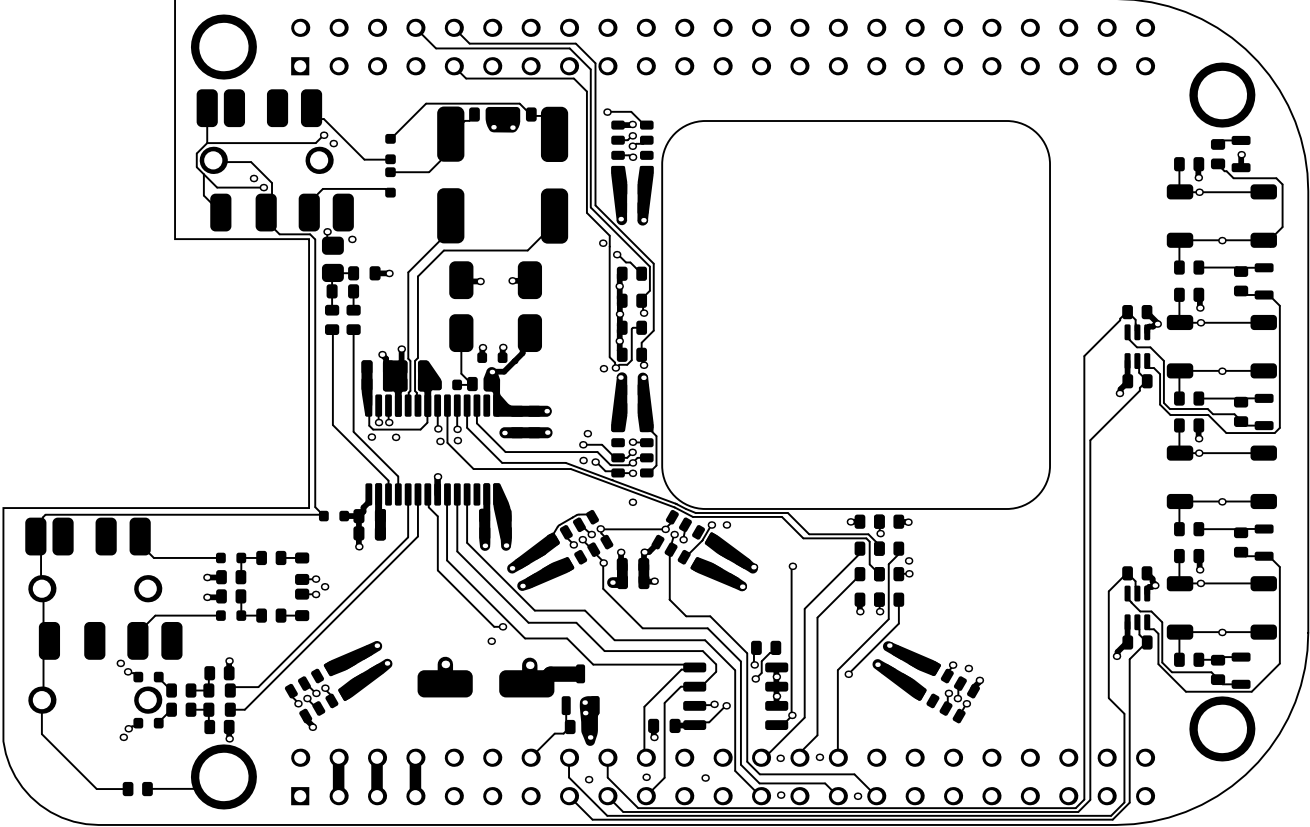
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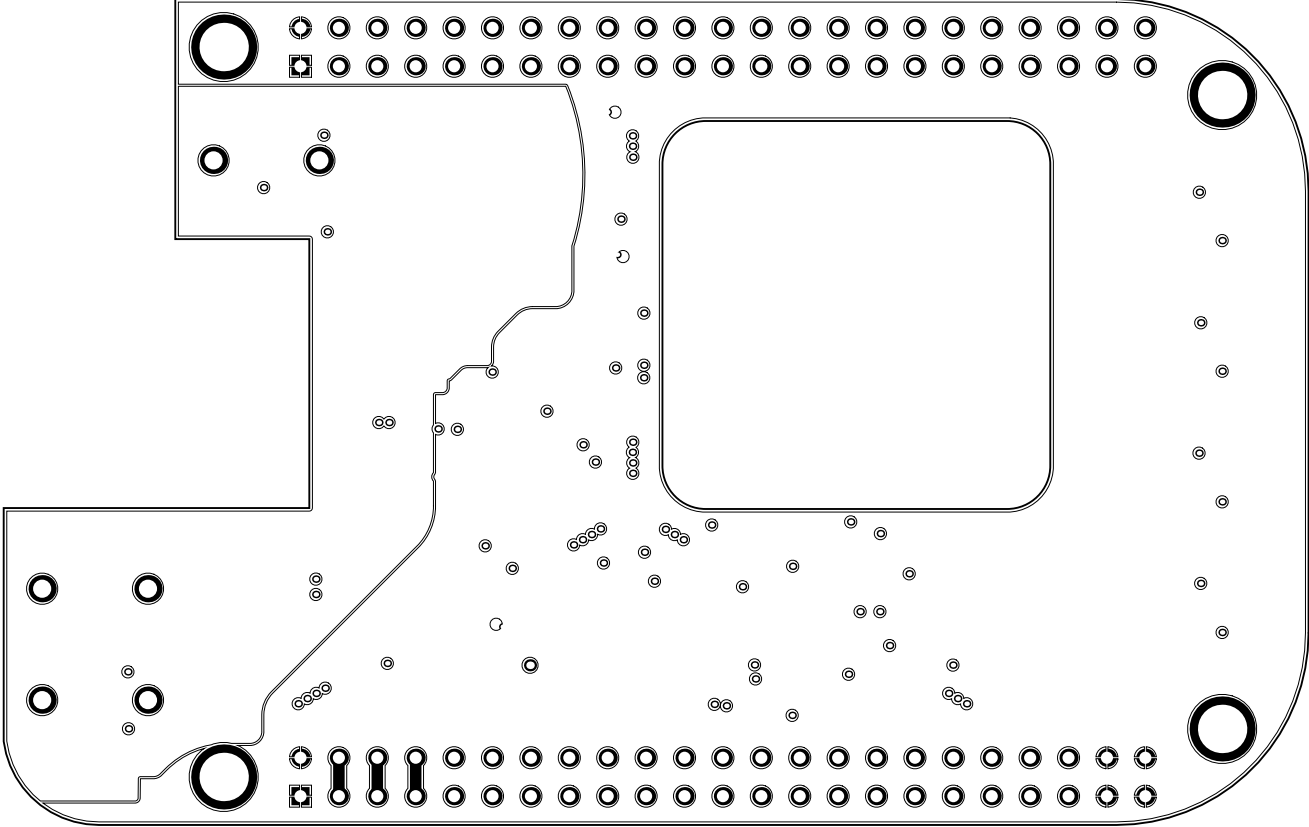
OF

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Technická 3058/10
616 00 Brno-Královo Pole

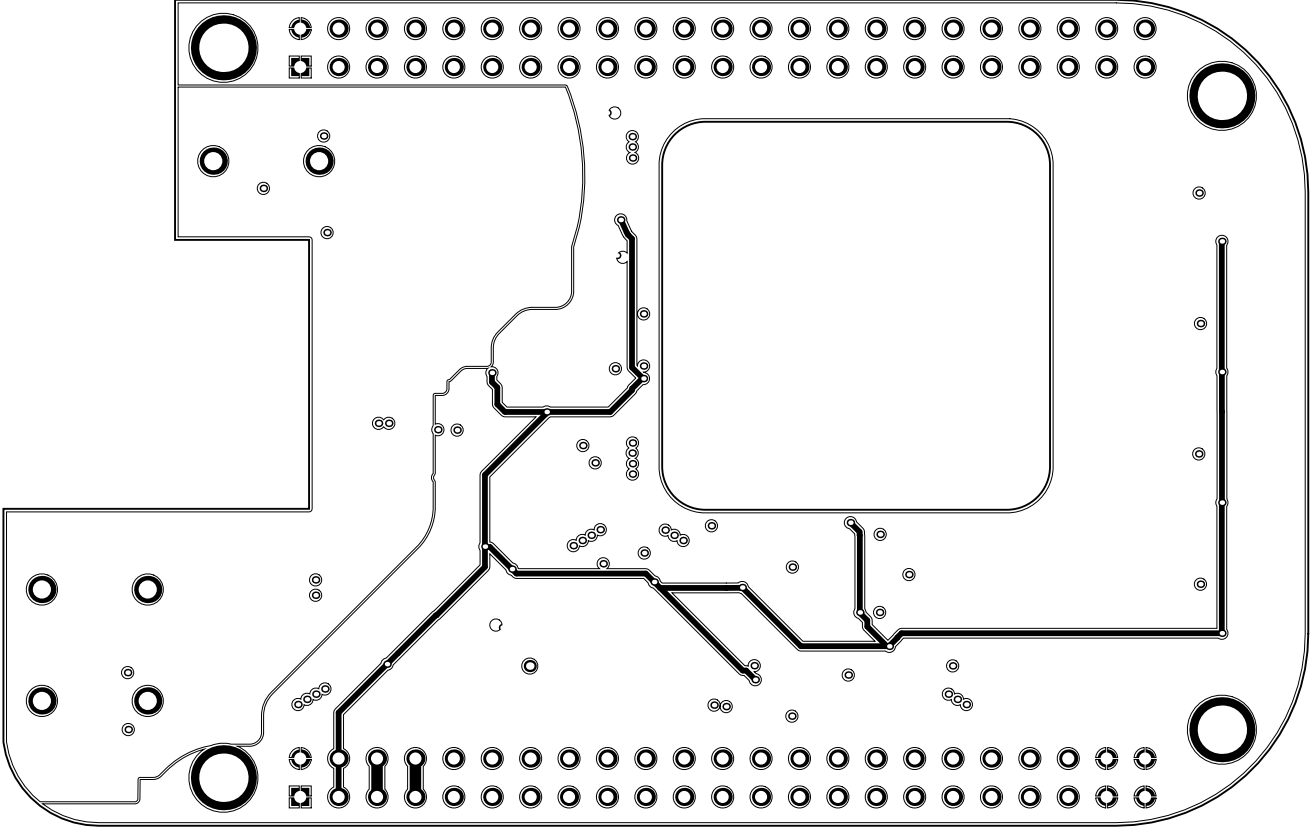
Top Layer (Scale: 2:1)



Mid Layer 1 (Scale: 2:1)



Mid Layer 2 (Scale: 2:1)



Bottom Layer (Scale: 2:1)

